

FIG. 1 (PRIOR ART)

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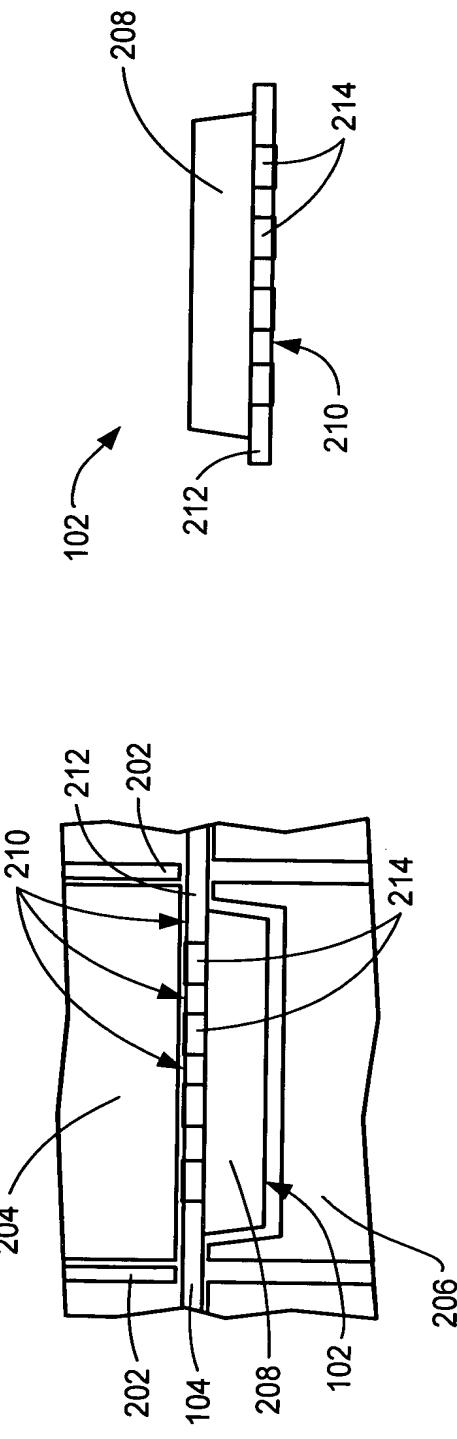


FIG. 2 (PRIOR ART)

FIG. 3 (PRIOR ART)

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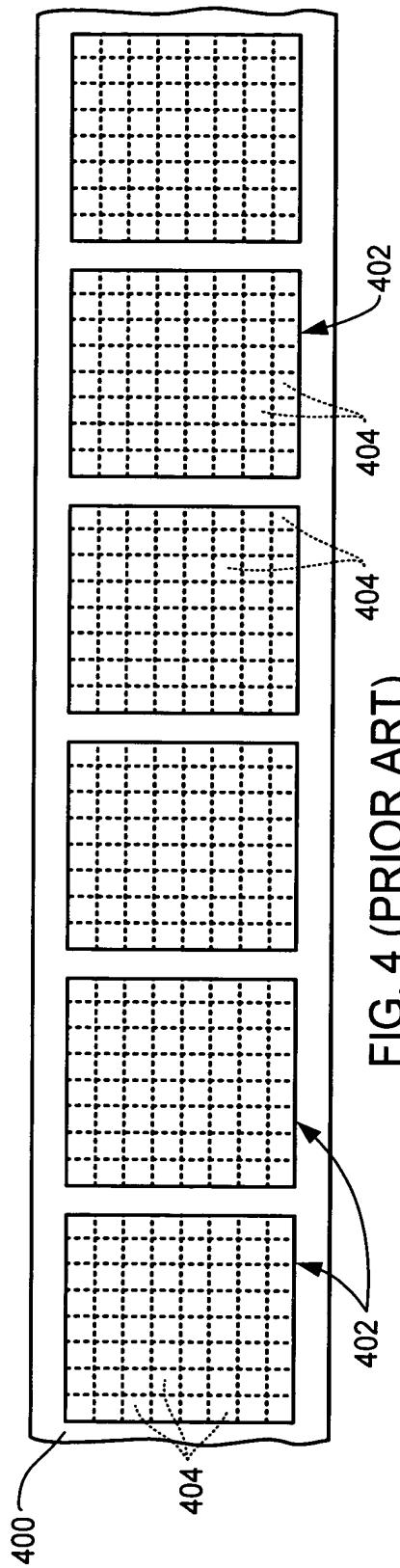


FIG. 4 (PRIOR ART)

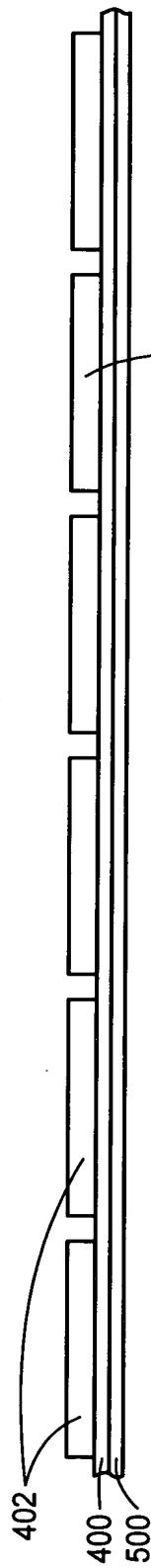


FIG. 5 (PRIOR ART)

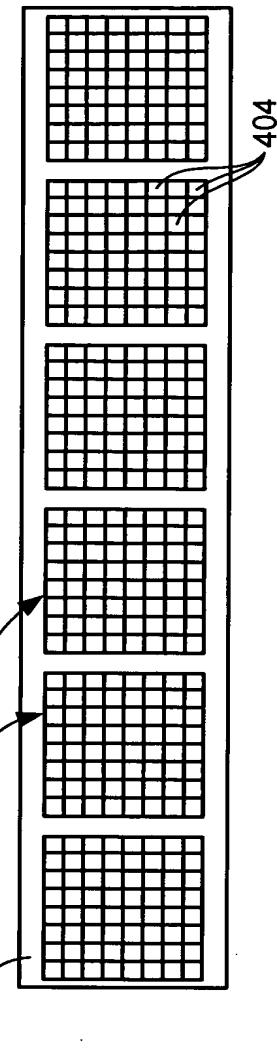


FIG. 7 (PRIOR ART)

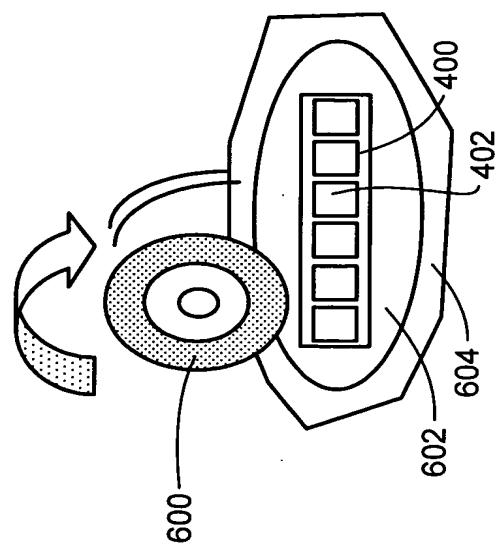
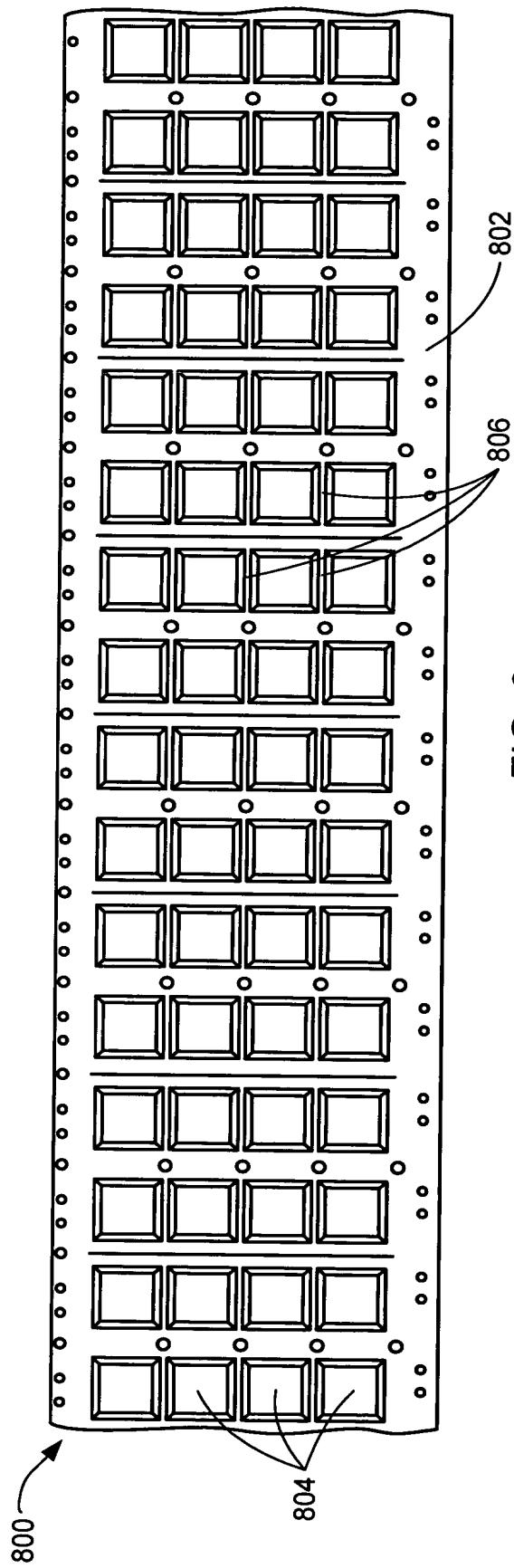


FIG. 6 (PRIOR ART)

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FIG. 8

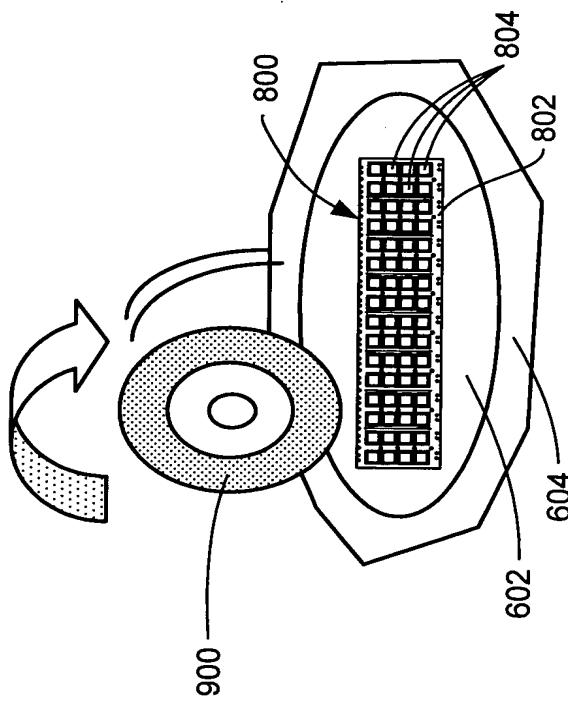
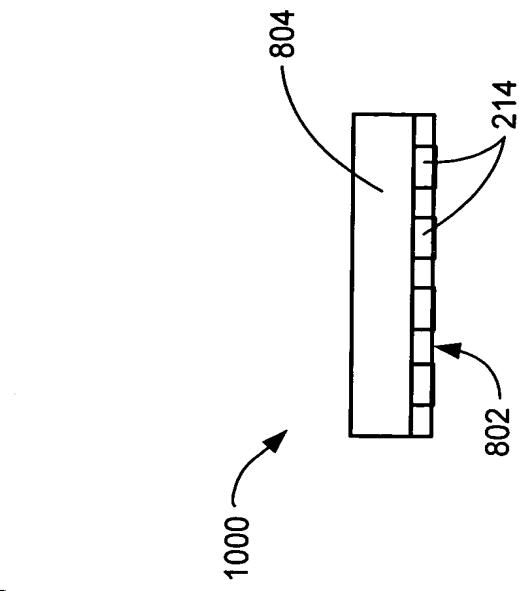


FIG. 10

FIG. 9

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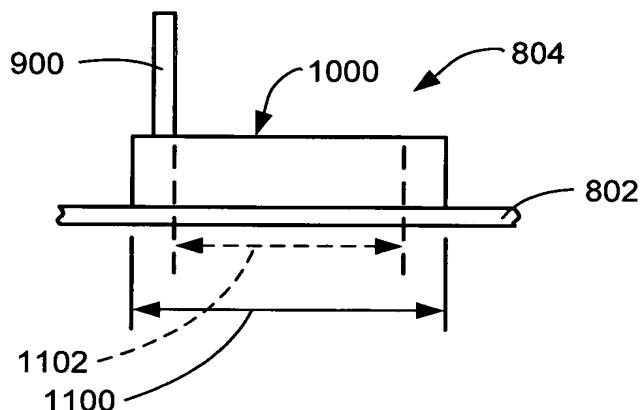


FIG. 11

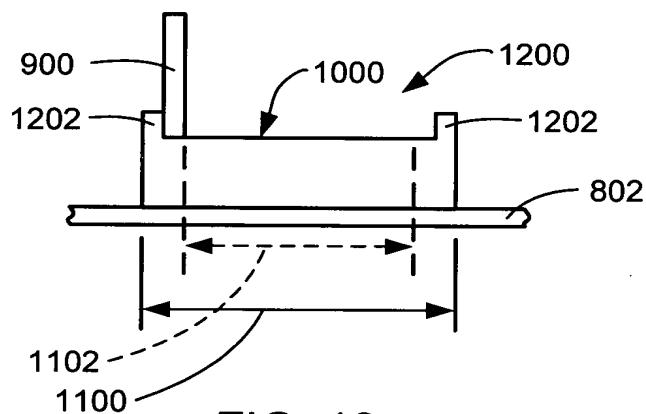


FIG. 12

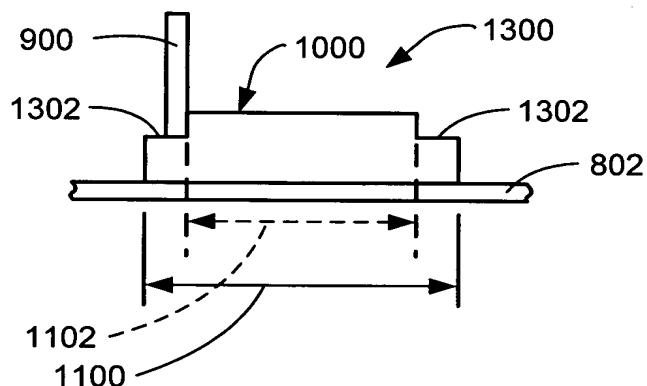


FIG. 13

Title: METHOD FOR FABRICATING  
SEMICONDUCTOR PACKAGES, AND LEADFRAME  
ASSEMBLIES FOR THE FABRICATION THEREOF  
Inventors: Byung Joon Han and Byung Hoon Ahn.  
Docket No.: 27-021  
Contact: Mikio Ishimaru (408) 738-0592

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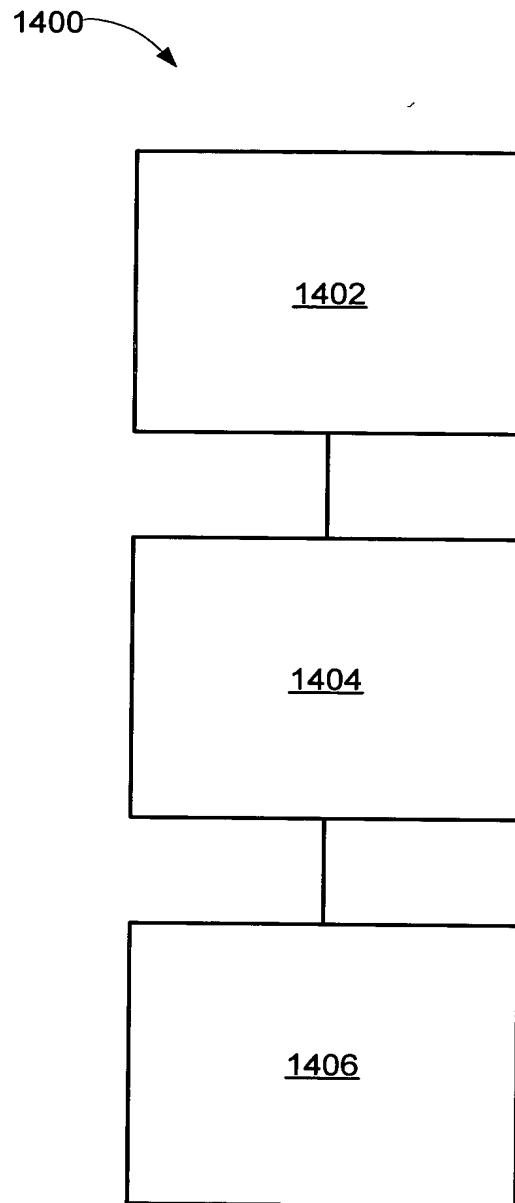


FIG. 14